



THINLAM®

Thin. Durable. Secure.

With a thickness of only 300 µm or less, the Linxens THINLAM® combines thin size with mechanical durability, long lifetime, and high performance. It is therefore ideally suited for contactless cards in automated fare collection, access control, and contactless payment applications.

Linxens THINLAM® consists of a core inlet which is sandwiched between two overlays. The product is available in both, HF and UHF. In terms of chip technology, Linxens draws upon its internal chip processing and module packaging capabilities.

The end product is a high-quality THINLAM® which ideally addresses card manufacturers' need for flexible card construction options.

Dimensions	Thickness*	Operating Temperature	Available ICs
From 3 x 6 up Max. 580 x 705 mm	300 µm ± 30 µm	-25°C to +50°C	Infineon NXP MIFARE family STMicroelectronics
From 3 x 6 up Max. 580 x 705 mm	300 µm ± 30 µm	-25°C to +50°C	Impinj NXP

Other thicknesses are available upon request.
Other chip types are available upon request.

RFID



Overview

Operating Frequency

- 13.56 MHz
- 860-960 MHz

Operating Temperature

- -25°C to +50°C

Material

- PVC, PC, PET-G

International Standards

- ISO 14443
- ISO 15693
- ISO 18000-6C

Application Area

- Access Control
- Contactless Payment
- Hospitality, Leisure & Entertainment

Options

- Initialization / customized programming of data

Benefits

- Very thin pre laminate
- High card surface quality